



BF861A; BF861B; BF861C

N-channel junction FETs

Rev. 5 — 15 September 2011

Product data sheet

1. Product profile

1.1 General description

N-channel symmetrical junction field effect transistors in a SOT23 package.

CAUTION



The device is supplied in an antistatic package. The gate-source input must be protected against static discharge during transport or handling.

1.2 Features and benefits

- High transfer admittance
- Low feedback capacitance
- Low input capacitance
- Low noise.

1.3 Applications

- Preamplifiers for AM tuners in car radios.

1.4 Quick reference data

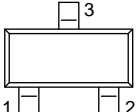

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)		-	-	25	V
I_{DSS}	drain current					
	BF861A	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	2	-	6.5	mA
	BF861B	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	6	-	15	mA
	BF861C	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	12	-	25	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25\text{ °C}$	-	-	250	mW
$ y_{fs} $	forward transfer admittance;					
	BF861A	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	12	-	20	mS
	BF861B	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	16	-	25	mS
	BF861C	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	20	-	30	mS
C_{iss}	input capacitance	$f = 1\text{ MHz}$	-	-	10	pF
C_{rss}	reverse transfer capacitance	$f = 1\text{ MHz}$	-	-	2.7	pF



2. Pinning information

Table 2. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	source		 sym053
2	drain		
3	gate		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BF861A	-	plastic surface mounted package; 3 leads	SOT23
BF861B	-	plastic surface mounted package; 3 leads	SOT23
BF861C	-	plastic surface mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
BF861A	28*
BF861B	29*
BF861C	30*

[1] * = p: Made in Hong Kong.

* = t: Made in Malaysia.

* = W: Made in China.

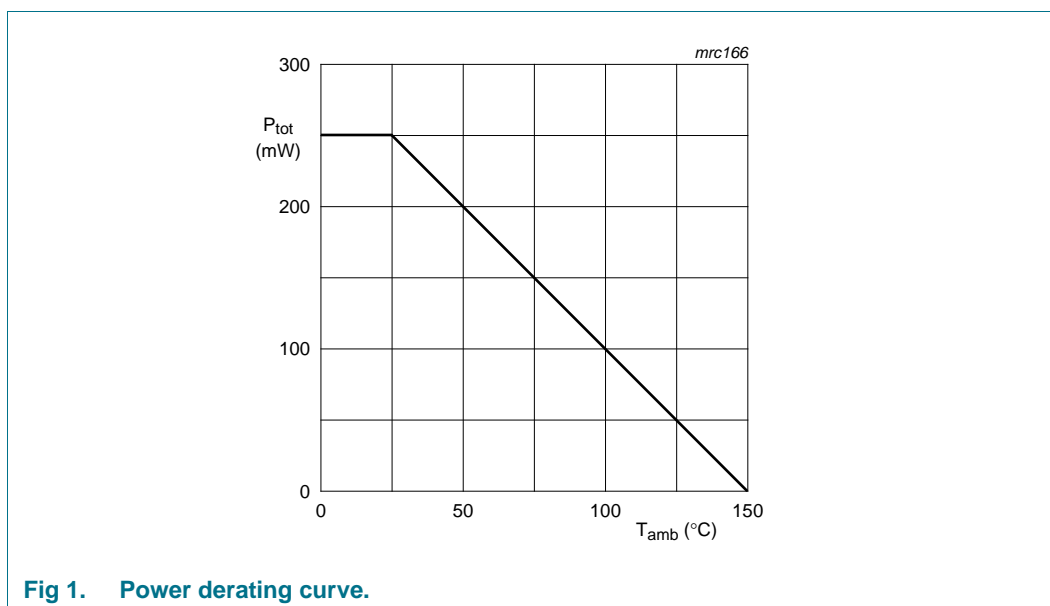
5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)		-	25	V
V_{GSO}	gate-source voltage	open drain	-	25	V
V_{DGO}	drain-gate voltage (DC)	open source	-	25	V
I_G	forward gate current (DC)		-	10	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25\text{ °C}$ [1]	-	250	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	operating junction temperature		-	150	°C

[1] Device mounted on an FR4 printed-circuit board.



6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1] 500	K/W

[1] Device mounted on an FR4 printed-circuit board.

7. Characteristics

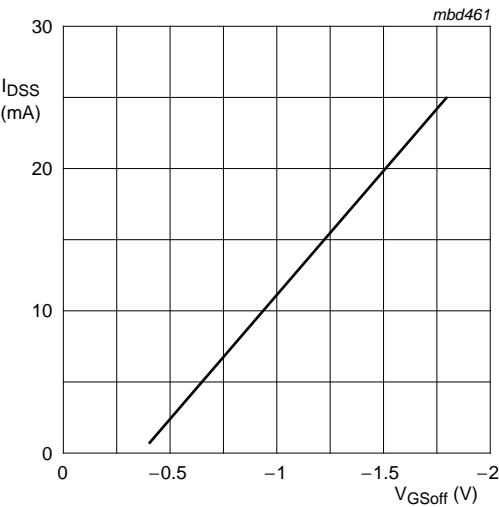
Table 7. Characteristics

$T_j = 25\text{ °C}$; $V_{DS} = 8\text{ V}$; $V_{GS} = 0\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)GSS}$	gate-source breakdown voltage	$I_G = -1\text{ }\mu\text{A}$	-25	-	-	V
V_{GSoff}	gate-source cut-off voltage					
	BF861A	$I_D = 1\text{ }\mu\text{A}$	-0.2	-	-1	V
	BF861B	$I_D = 1\text{ }\mu\text{A}$	-0.5	-	-1.5	V
	BF861C	$I_D = 1\text{ }\mu\text{A}$	-0.8	-	-2	V
V_{GSS}	gate-source forward voltage	$V_{DS} = 0\text{ V}$; $I_G = 1\text{ mA}$	-	-	1	V
I_{DSS}	drain current					
	BF861A		2	-	6.5	mA
	BF861B		6	-	15	mA
	BF861C		12	-	25	mA
I_{GSS}	gate cut-off current	$V_{GS} = -20\text{ V}$; $V_{DS} = 0\text{ V}$	-	-	-1	nA

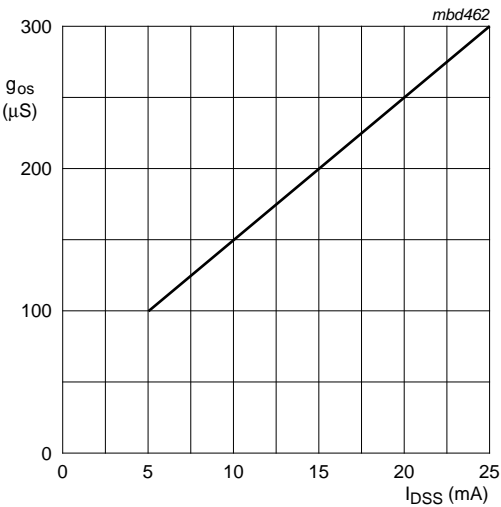
Table 7. Characteristics ...continued
T_j = 25 °C; V_{DS} = 8 V; V_{GS} = 0 V unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
y _{fs}	forward transfer admittance					
	BF861A		12	-	20	mS
	BF861B		16	-	25	mS
	BF861C		20	-	30	mS
g _{os}	common source output conductance					
	BF861A		-	-	200	μS
	BF861B		-	-	250	μS
	BF861C		-	-	300	μS
C _{iss}	input capacitance	f = 1 MHz	-	-	10	pF
C _{rss}	reverse transfer capacitance	f = 1 MHz	-	2.1	2.7	pF
V _n /√B	equivalent input noise voltage	V _{GS} = 0 V; f = 1 MHz	-	1.5	-	nV/√Hz



V_{DS} = 8 V.

Fig 2. Drain current as a function of gate-source cut-off voltage; typical values.



V_{DS} = 8 V.
V_{GS} = 0 V.

Fig 3. Common-source output conductance as a function of drain current; typical values.

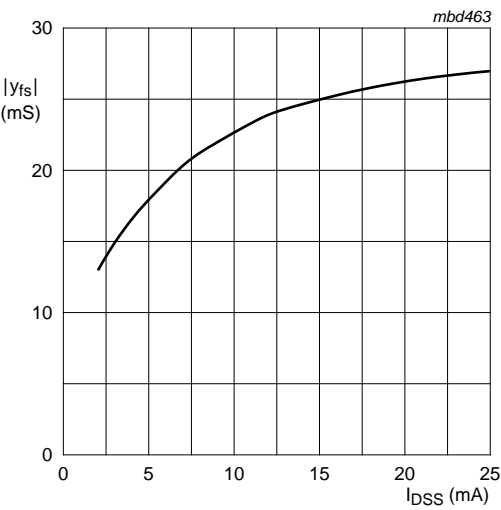


Fig 4. Forward transfer admittance as a function of drain current; typical values.

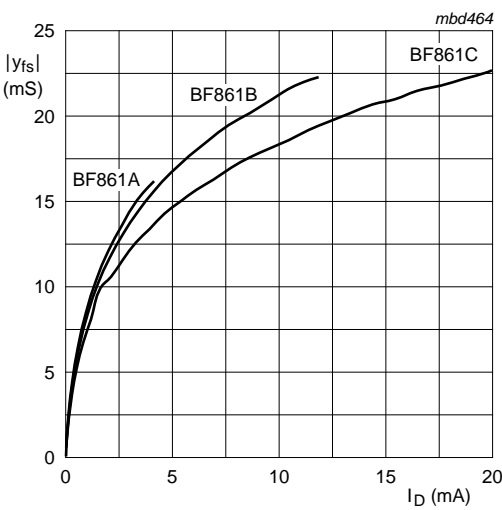


Fig 5. Forward transfer admittance as a function of drain current; typical values.

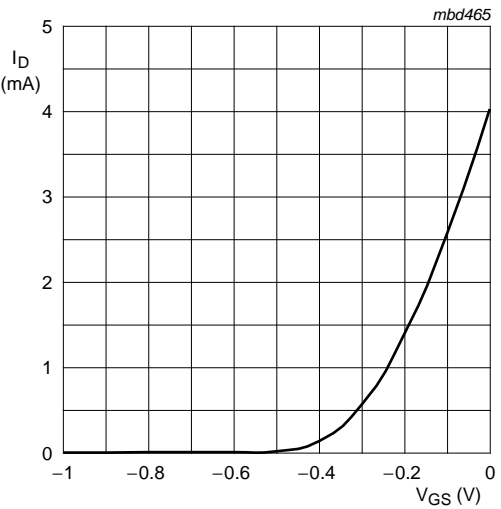


Fig 6. Typical input characteristics; BF861A.

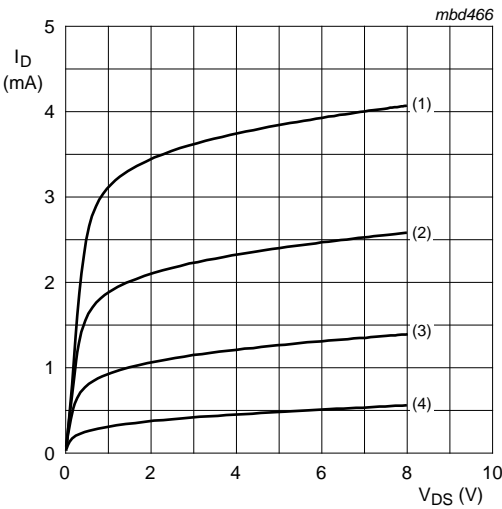
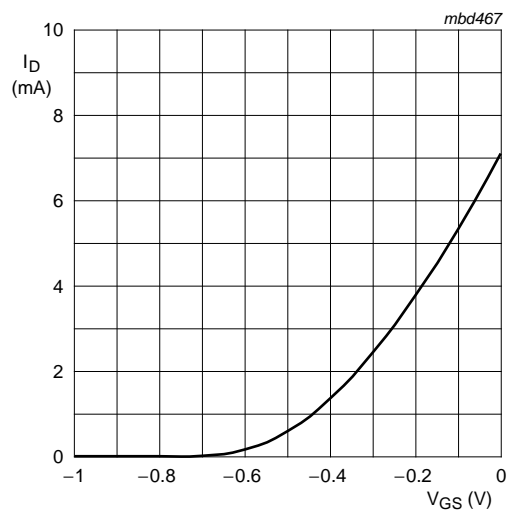
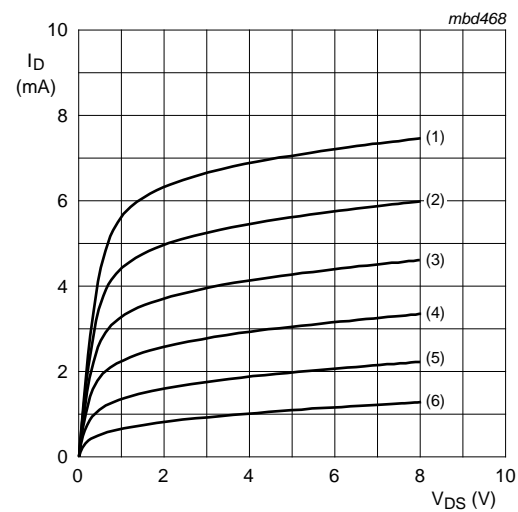


Fig 7. Typical output characteristics: BF861A.



$V_{DS} = 8\text{ V.}$

Fig 8. Typical input characteristics; BF861B.



$V_{DS} = 8\text{ V.}$

- (1) $V_{GS} = 0\text{ V.}$
- (2) $V_{GS} = -100\text{ mV.}$
- (3) $V_{GS} = -200\text{ mV.}$
- (4) $V_{GS} = -300\text{ mV.}$
- (5) $V_{GS} = -400\text{ mV.}$
- (6) $V_{GS} = -500\text{ mV.}$

Fig 9. Typical output characteristics; BF861B.

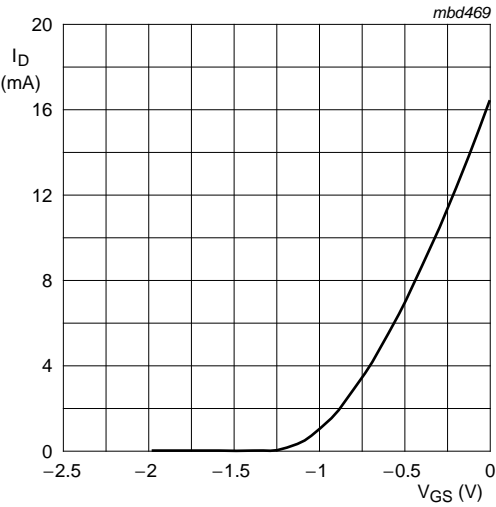


Fig 10. Typical input characteristics; BF861C.

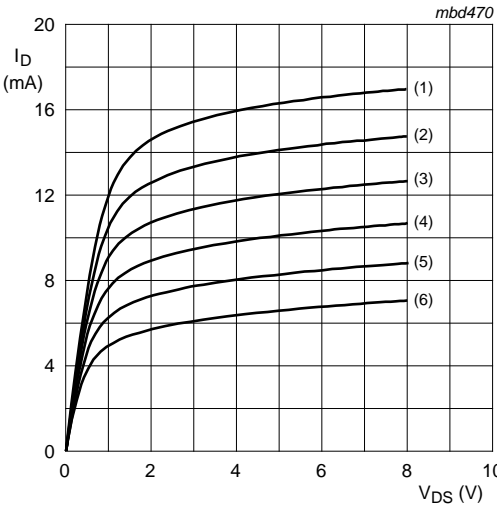


Fig 11. Typical output characteristics; BF861C.

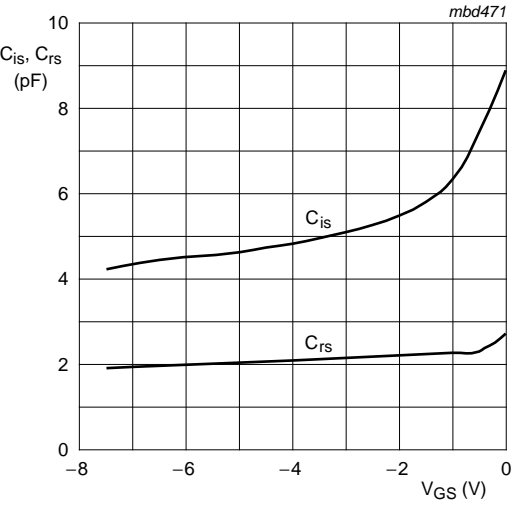


Fig 12. Input and reverse transfer capacitance as functions of gate-source voltage; typical values.

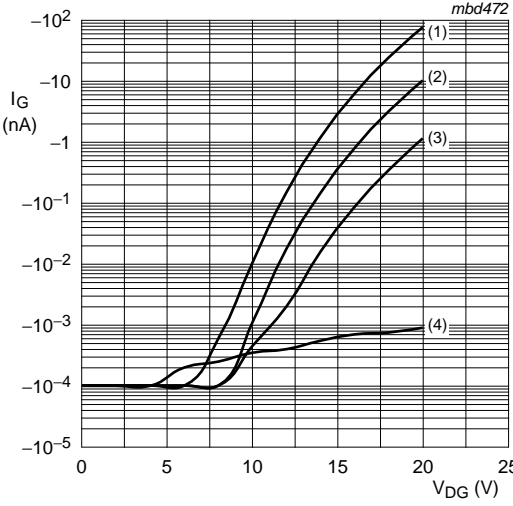
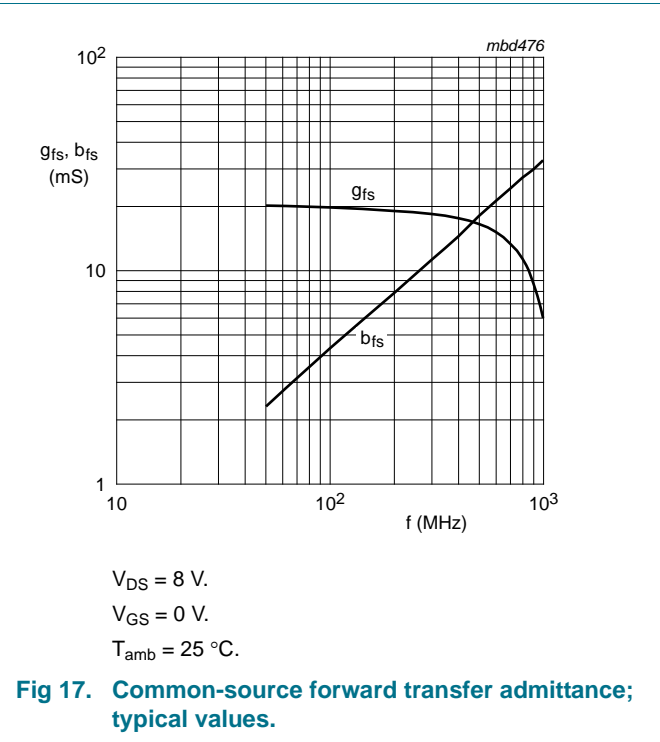
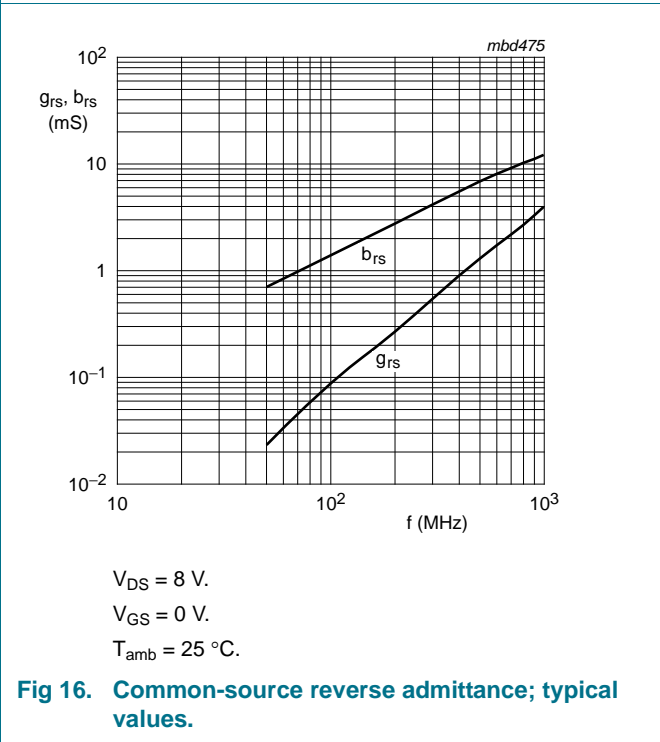
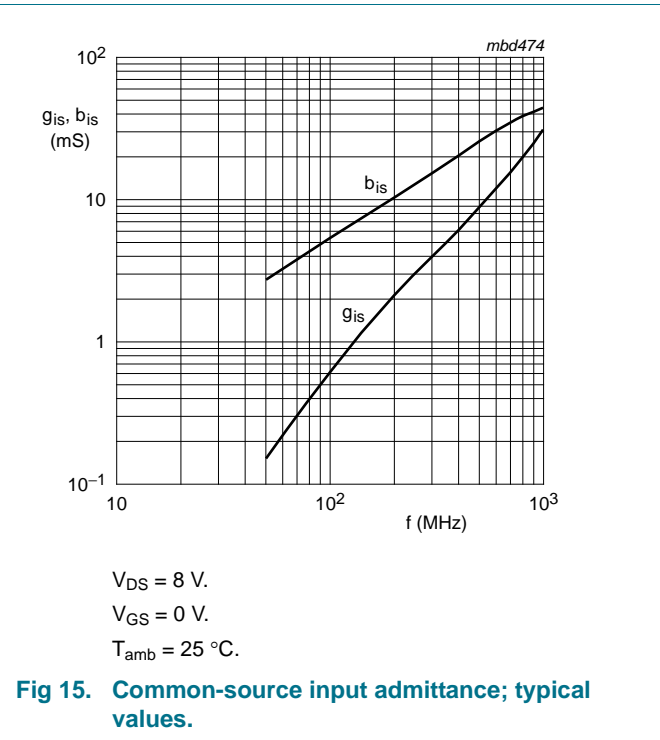
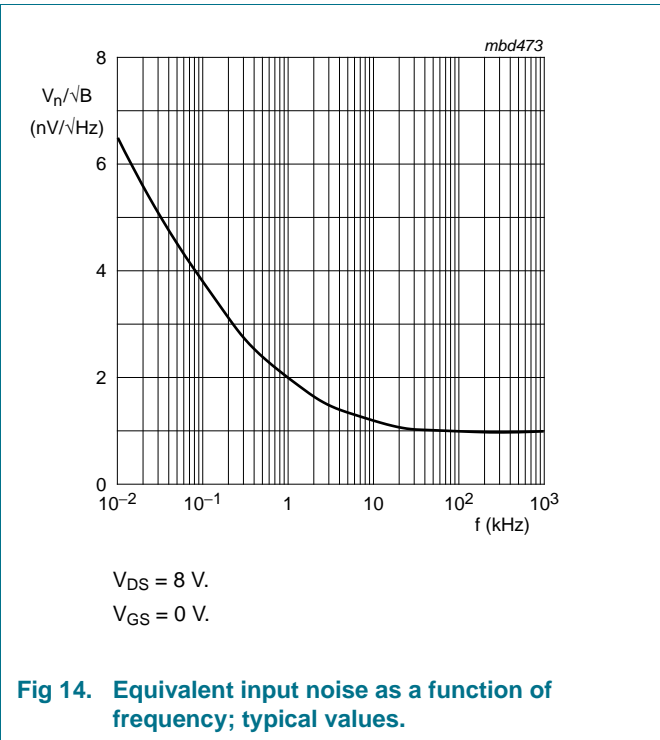
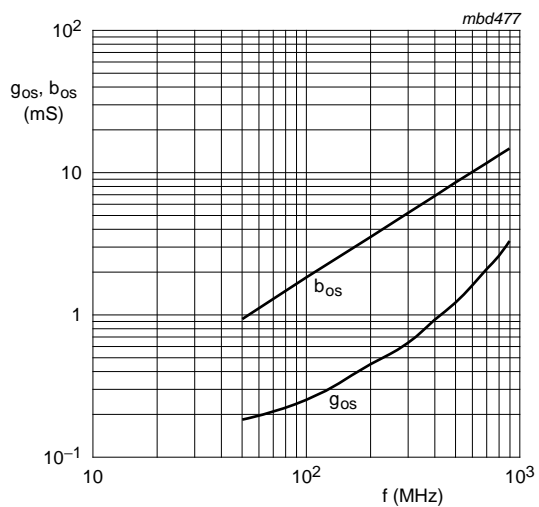


Fig 13. Gate current as a function of drain-gate voltage; typical values.





$V_{DS} = 8 \text{ V.}$
 $V_{GS} = 0 \text{ V.}$
 $T_{amb} = 25 \text{ }^{\circ}\text{C.}$

Fig 18. Common-source output admittance; typical values.

8. Package outline

Plastic surface-mounted package; 3 leadsSOT23

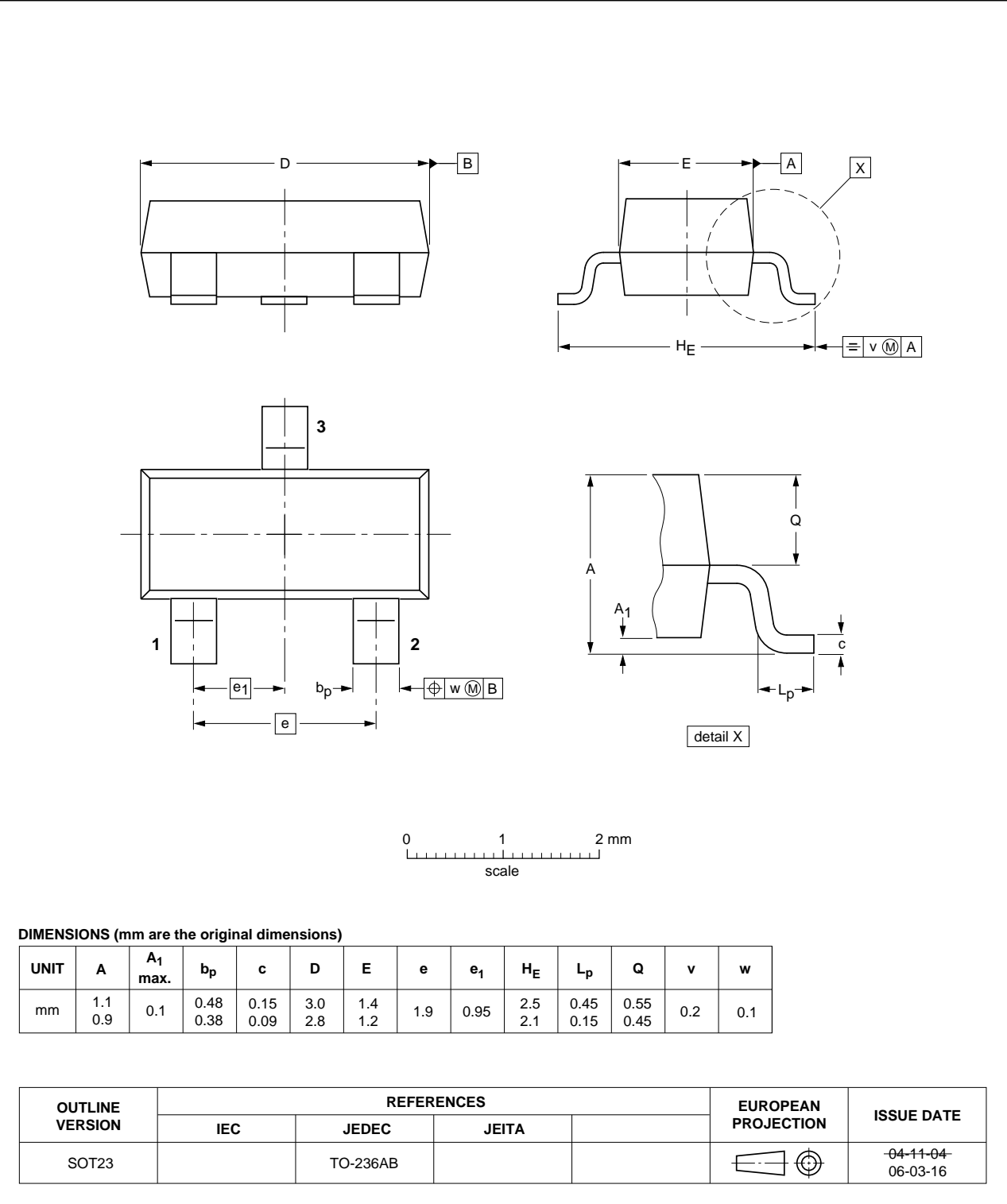


Fig 19. Package outline

9. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BF861A_BF861B_BF861C v.5	20110915	Product data sheet	-	BF861A_BF861B_BF861C v.4
Modifications:	<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• Package outline drawings have been updated to the latest version.			
BF861A_BF861B_BF861C v.4 (9397 750 13395)	20040924	Product data sheet	-	BF861 v.3
BF861 v.3 (9397 750 02667)	19970904	Product specification	-	BF861 v.2
BF861 v.2	19950414	-	-	BF861 v.1
BF861 v.1	19940829	-	-	-

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10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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